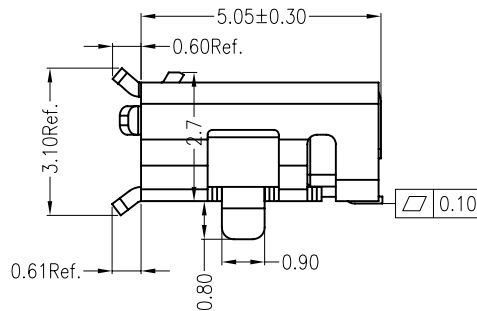
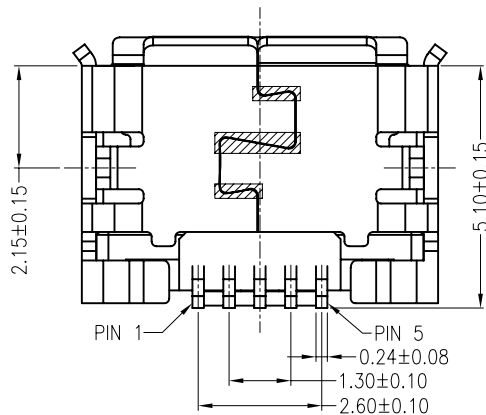
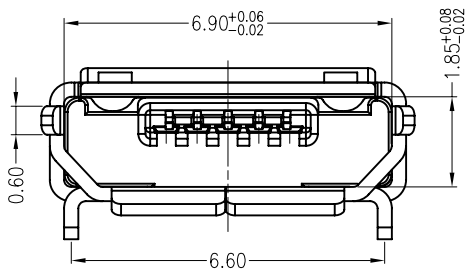
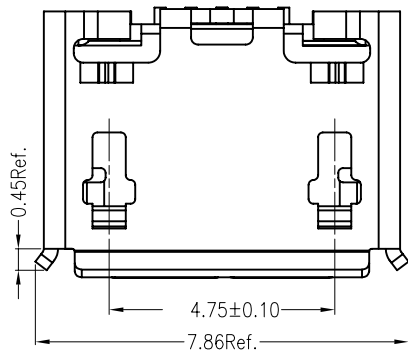
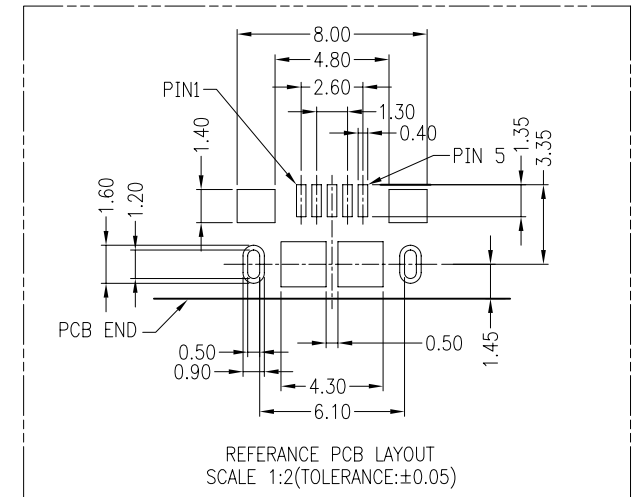


THE PART MEETS TECONN "GP001" COMPLIANCE



A4A0504-B-XX-R

Mating Area plating

01: Au 1u"Min.
03: Au 3u"Min.
05: Au 5u"Min.
10: Au 10u"Min.
15: Au 15u"Min.
30: Au 30u"Min.

- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

Item	Title	Material	Dispose
1	Shell	Stainless Steel	Matte Tin 80u"min.
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:Gold 2u"min.
3	InsertMolding	LCP	UL94V-0

X. ± 0.35	APPD:	TITLE:	 泰康电子 TECONN
.X ± 0.25	CHKD:	MICRO USB B/F 5PIN SMT	
.XX ± 0.15	DR: Kevin Han	PART NO: A4A0504-B-XX-R	
.XXX±		DWG NO: CUSTOMER DRAWING	
X* ± 2*		C-A4A0504-B-XX-R	SHEET:10F1
.X* ± 1.5*			REV: A

A	TE2011-0016	New Drawing	2011/01/11
REV	ECN NO	DESCRIPTION	DATE